

PCB LAYOUT \* - COMPONENT VIEW

#### TECHNICAL CHARACTERISTICS

##### MATERIAL

INSULATOR: LCP

FLAMABILITY RATING: UL94-V0

COLOR: BLUE

CONTACT MATERIAL: PHOSPHORE BRONZE

CONTACT TYPE: STAMPED

CONTACT PLATING: UNDERPLATE 1.27 to 2.54  $\mu\text{m}$  Ni

CONTACT AREA 0.76  $\mu\text{m}$  Gold

SOLDER TAIL AREA 2.54 to 5.08  $\mu\text{m}$  Matt Tin

SHIELDING: BRASS MATT TIN PLATED

##### ENVIRONMENTAL

OPERATING TEMPERATURE: -20 up to +85°C

COMPLIANCE: RoHS & LEAD FREE AS PER DIRECTIVE 2002/95/EC

HALOGEN FREE COMPLIANT AS PER IEC 61249-2-21

##### ELECTRICAL

CURRENT RATING:

- PIN 1 & PIN 4 (Vbus & corresponding ground PIN) 1.8A Max

- OTHER PINS 0.25 A Max

WORKING VOLTAGE: 30Vac

DIELECTRIC WITHSTANDING VOLTAGE: 100Vac/min

INSULATION RESISTANCE: > 100M $\Omega$

CONTACT RESISTANCE:

- PIN 1 & PIN 4: 30m $\Omega$  Max

- OTHER PINS: 50m $\Omega$  Max

##### STANDARD

 CERTIFIED: E323964 / MODEL NUMBER 692121230100

##### MECHANICAL

INSERTION FORCE: 35.0N Max

EXTRACTION FORCE: 10.0N min

QUALITY CLASS: 5000 MATING CYCLES

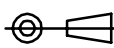

##### SOLDERING

REFLOW PROCESS ONLY AS PER JEDEC J-STD-020D

##### PACKAGING

TAPE & REEL

\* NOTE: THE RECOMMENDED PCB LAYOUT IS FOR AN OPTIMIZED RETENTION FORCE OF CONNECTOR ON PCB BUT IT IMPLIES INSERTION FORCE THAT A LOT OF PICK AND PLACE MACHINES ARE NOT ABLE TO HANDLE. THEREFORE IT MIGHT BE NECESSARY TO DRILL BIGGER HOLES FOR THE CLIPS. PLEASE CHECK THIS CAREFULLY.

RoHS Compliant				NOTE: THE RECOMMENDED PCB LAYOUT IS FOR AN OPTIMIZED RETENTION FORCE OF CONNECTION ON PCB BUT IT IMPLIES INSERTION FORCE THAT A LOT OF PICK AND PLACE MACHINES ARE NOT ABLE TO HANDLE. THEREFORE IT MIGHT BE NECESSARY TO DRILL BIGGER HOLES FOR THE CLIPS. PLEASE CHECK THIS CAREFULLY.				
G				<div>PROJECTION:</div> <div></div>	GENERAL TOLERANCE	<div></div> <div>WÜRTH ELEKTRONIK</div>		
F					.X = $\pm$ 0.2			
E	12-AUG-13	CHARACTERISTIC	QL		.XX = $\pm$ 0.15			
D	09-NOV-11	STENCIL	GG					
C	21-SEP-11	NOTE	GG	APPROVAL: RJ	UNIT: MM	DESCRIPTION: USB 3.0 HORIZONTAL TYPE A WITH OFFSET 1.04 MM		SIZE <b>A4</b>
B	10-MAY-11	UL	GG		SCALE:			
A	16-SEP-10	PDF	JP		SHEET: 1/3	WERI PART NO: 692 121 230 100		
REV	DATE	FILE	BY		DRAW: JOE			

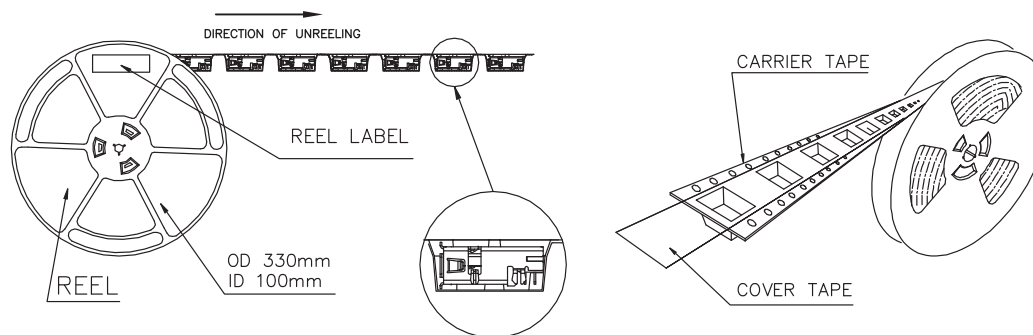
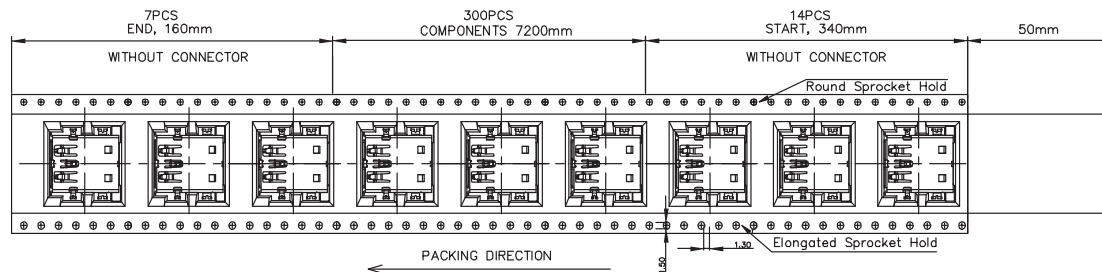
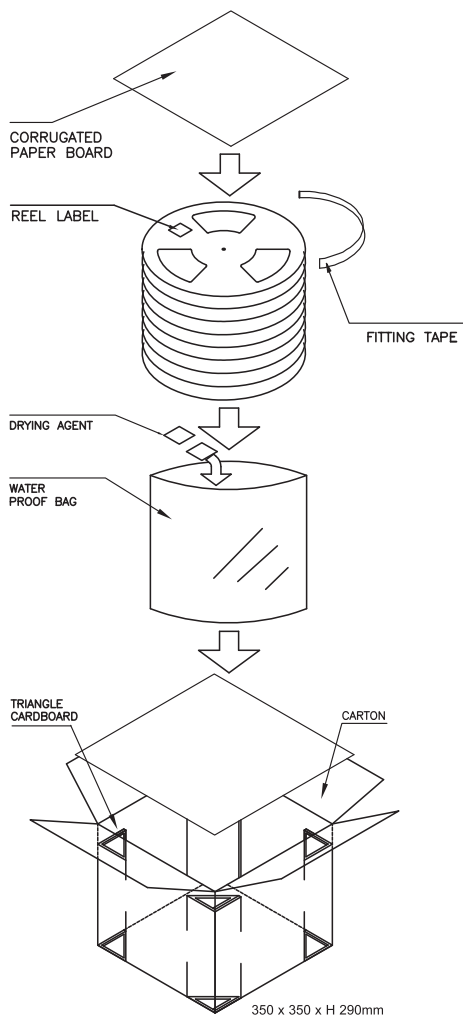
1

2

3

4

5



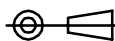
## NOTES

1. MATERIALS: PS
2. 1500PCS/CARTON
3. RoHS

All Material in According With The Rohs Environment  
Related Substances List Controlled.

RoHS Compliant

PROJECTION:



GENERAL TOLERANCE

.X =  $\pm 0.2$ .XX =  $\pm 0.15$ 

APPROVAL: RJ

UNIT: MM

SCALE:

SHEET: 2/3

DRAW: JOE

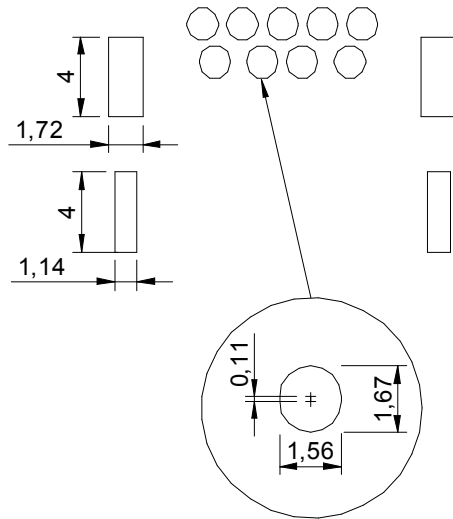
DESCRIPTION: USB 3.0 HORIZONTAL TYPE A WITH OFFSET 1.04 MM

WERI PART NO: 692 121 230 100

SIZE

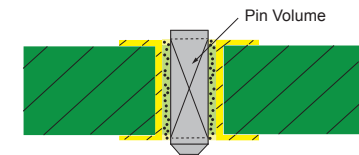
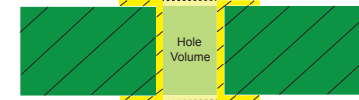
A4

# Stencil information for Through Hole Reflow soldering



STENCIL LAYOUT \* - COMPONENT VIEW

## PCB cross section



 Free volume for solder paste

Theoretical Formula for Through Hole pins

Volume of the stencil aperture = (Hole volume - Pin volume) x 2

or

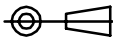

Volume of solder paste = (Hole volume - Pin volume) x 2

Stencil

Stencil Thickness: 150 µm

PCB

PCB thickness: 1.6mm

RoHS Compliant		* NOTE: SEE PCB LAYOUT PAGE 1/3 FOR MISSING DIMENSIONS					
G				<div>PROJECTION:</div> <div></div>	<div>GENERAL TOLERANCE</div> <div>.X = +/- 0.2</div> <div>.XX = +/- 0.15</div>	<div></div> <div>WÜRTH ELEKTRONIK</div>	
F							
E							
D							
C				APPROVAL: RJ	UNIT: MM	DESCRIPTION: USB 3.0 HORIZONTAL TYPE A WITH OFFSET 1.04 MM	SIZE <b>A4</b>
B					SCALE:		
A					SHEET: 3/3	WERI PART NO: 692 121 230 100	
REV	DATE	FILE	BY		DRAW: JOE		